



E-Song America, Inc.

100%
RoHS Compliant
Products

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SILICONE SHEET FOR BONDING PROCESS: HEA Series

Characteristic

HEA-5010 and HEA-8010 are specifically designed as cushion sheet with high thermal conductivity and high restoration ability. This material is used for assembling TFT-LCD modules, where the electrode thermal connector of crystal panel is assembled with flexible printed circuit board (ACF bonding). It uniformly distributes heat and pressure between the heating tool and the connector, so that no damage can be caused to PCB either by heat or pressure during processing.

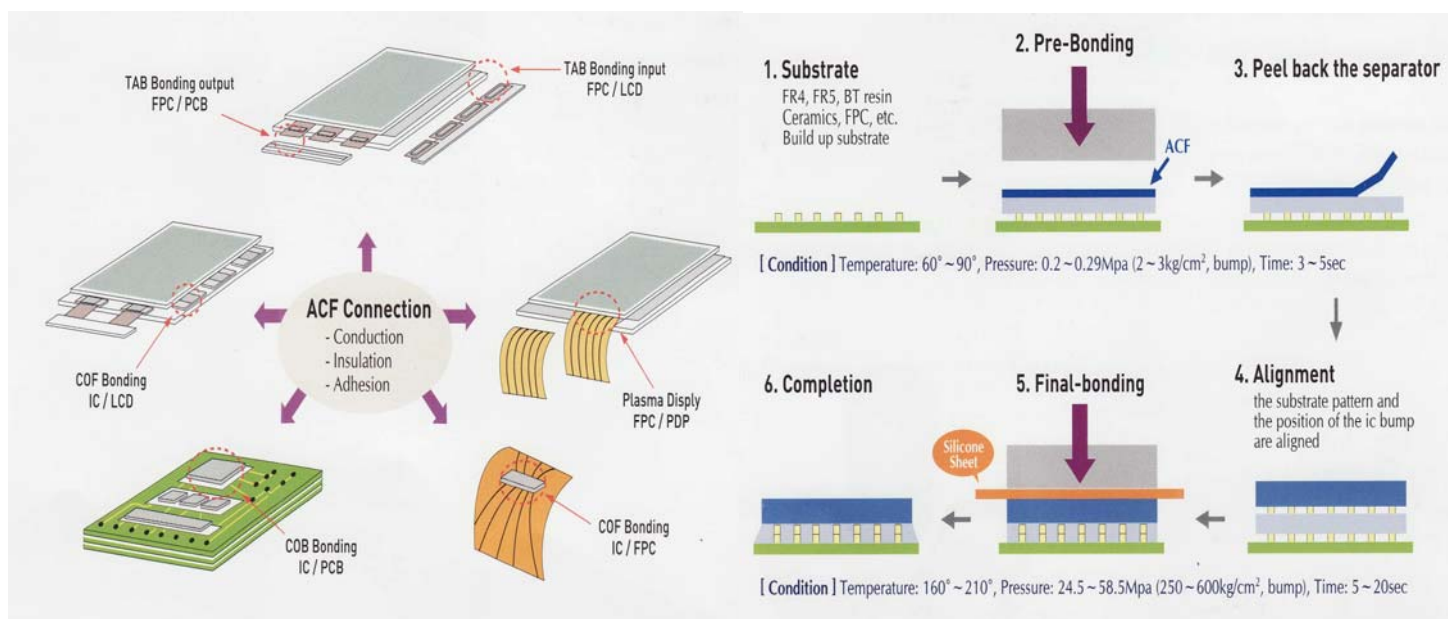
Key Features: * High thermal conductivity and softness provides fast and uniform heat transfer without damaging PCB

- * High heat stability
- * Creates no dust
- * High tear strength
- * High restration characteristics
- * Electrical insulation properties



Suggested Applications

* AFC Bonding Process, FOG Bonding Process, TAB Bonding Process, COB & COF Bonding Process



Technical data

	HEA-5010	HEA-8010
Thickness (mm)	0.20 ^{±0.02} , 0.25 ^{±0.02} , 0.35 ^{±0.03} , 0.45 ^{±0.03}	0.20 ^{±0.02} , 0.25 ^{±0.02} , 0.35 ^{±0.03} , 0.45 ^{±0.03}
Color	Black	Gray
Thermal Conductivity (W/mk)	0.8	1.0
Specific Gravity (g/cm ³)	1.70	2.20
Hardness (Shore A)	60	75
Tensile Strength (MPa)	8	5
Elongation (%)	150	120
Tear Strength (KN/m)	12	12
Volume Resistivity (ohm-meter)	2.0 x 10 ⁹	5.0 x 10 ⁹⁻¹⁴
Maximum Usage Temp. (°C)	450	450

Note: These values are for reference only. Actual application performance is dependent on surface roughness, flatness and pressure applied.